



FORM PTO-1449

INFORMATION DISCLOSURE CITATION

Attorney Docket:
4024-4021Serial No.:
09/897,158Applicant:
Dudoff et al.Filing Date:
June 29, 2001Group Art Unit:
2814

U.S. PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Name	Class	Sub-Class	Filing Date
<i>DSE</i>	4,533,833		Copeland et al.			August 6, 1985
	5,266,794		Olbright et al.			November 30, 1993
	5,269,453		Melton et al.			December 14, 1993
	5,385,632		Goossen			January 31, 1995
	5,477,933		Nguyen			December 26, 1995
	5,793,789		Ben-Michael et al.			April 11, 1998
	6,005,262		Cunningham			December 21, 1999
	6,048,751		D'Asaro et al.			April 11, 2000
	6,172,417		Goossen			September 1995
	6,184,066		Chino et al.			February 6, 2001
	6,253,986		Brofman			July 3, 2001
	6,283,359		Brofman			September 4, 2001
	6,340,113		Avery et al.			January 22, 2002
	6,343,171		Yoshimura et al.			June 29, 2002
	Pub. No. US2001 /00207939		Honda			September 13, 2001
	Pub. No. US2001 0038103		Nitta et al			November 8, 2001
	Pub. No. US2001 0081773		Inoue et al.			June 27, 2002

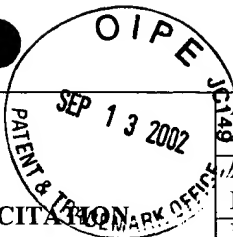
Examiner

Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609.
Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to Applicant.

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FOREIGN PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Country	Class	Sub-Class	Translation
						<input type="checkbox"/> Yes <input type="checkbox"/> No
						<input type="checkbox"/> Yes <input type="checkbox"/> No
						<input type="checkbox"/> Yes <input type="checkbox"/> No

OTHER DOCUMENTS (continued)

<i>Dte</i>	Ahadian, J.F., et al., "Practical OEIC's Based on the Monolithic Integration of GaAs-InGap LED's with Commercial GaAs VLSI Electronics", IEEE Journal of Quantum Electronics, Vol. 34, No. 7, pages 1117-1123, July 1998.
	Alduino, A.C. et al., "Quasi-Planar Monolithic Integration of High-Speed VCSEL and Resonant Enhanced Photodetector Arrays", IEEE Photonics Technology Letters, Vol. 11, No. 5, pages 512-514, May 1999.
	Anderson, B., "Rapid Processing And Properties Evaluation Of Flip-Chip Underfills", Dexter Electronic Materials, 9 pages.
	Corbett, B. et al., "Resonant Cavity Light Emitting Diode and Detector Using Epitaxial Liff-off", IEEE, Vol. 5, No. 9, pages 1041-1043, September 1993.
	Geib, K.M. et al., "Monolithically Integrated VCSELs and Photodetectors for Microsystem Applications", IEEE, pages 27-28, 1998.
	Goodman, J. et al., "Optical Interconnections for VLSI Systems", Proceedings of the IEEE, Vol. 72, No. 7, pages 850-865, July 1984.
	Goossen, K. W. et al., "GaAs 850 nm Modulators Solder-Bonded to Silicon", IEEE Photonics Technology Letters, Vol. 5, No. 7, July 1993.
	Goossen, K.W. et al., "GaAs MQW Modulators Integrated with Silicon CMOS", IEEE Photonics Technology Letters, Vol. 7, No. 4, pages 360-362, April 1995.
	Hibbs-Brenner, M.K., et al., "VCSEL/MSM Detector Smart Pixel Arrays", IEEE, pages 3 and 4, 1998.
	Lesser, M.P. et al., "Bump Bonded Back Illuminated CCDs", SPIE, Vol. 1656, pages 508-516, 1992.
	McLaren T. et al., "Assembly of VCSEL Based Smart Pixel Arrays", IEEE/LEOS Summer Topical Meeting: Smart Pixels, pages 49 and 50, August 1996.
	Nakahara, T., et al., "Hybrid Integration of Smart Pixels by Using Polyimide Bonding: Demonstration of a GaAs p-i-n Photodiode/CMOS Receiver", IEEE Journal Of Selected Topics In Quantum Electronics, pages 209-216, 1999.



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OTHER DOCUMENTS (continued)

<i>DX</i>	Ohsaki, T., "Electronic Packaging in the 1990's -A Perspective From Asia", IEEE Transactions On Components, Hybrids, And Manufacturing Technology, Vol. 14, No. 2, pages 254-261, June 1991.		
<i>[Handwritten mark]</i>	Pommerrenig, D.H. et al., "Hybrid silicon focal plane development: an update", SPIE, Vol. 267, pages 23-30, 1981.		
<i>[Handwritten mark]</i>	Pu, R. et al., "Comparison of Techniques for Bonding VCSELs Directly to ICs", SPIE Vol. 3490, pages 498-501, June 2005.		
<i>[Handwritten mark]</i>	Pu, R. et al., "Hybrid Integration of VCSELs to Foundry Fabricated Smart Pixels", IEEE/LEOS Spring Meetings, pages 25 and 26, 1997.		
<i>[Handwritten mark]</i>	Sasaki, J. et al., "Self-aligned Assembly Technology for Optical Devices Using AuSn Solder Bumps Flip-Chip Bonding", pages 260-261.		
Examiner	<i>Douglas Wille</i>	Date Considered	<i>6 nov 02</i>
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.			